SDLS007

D2635, JANUARY 1981-REVISED MARCH 1988

- 8-Bit Parallel Storage Register Inputs ('LS597)
- Parallel 3-State I/O, Storage Register Inputs, Shift Register Outputs ('LS598)
- Shift Register has Direct Overriding Load and Clear
- Accurate Shift-Frequency . . . DC to 20 MHz

description

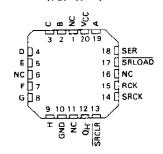
The 'LS597 comes in a 16-pin package and consists of an 8-bit storage latch feeding a parallel-in, serial-out 8-bit shift register. Both the storage register and shift register have positive-edge triggered clocks. The shift register also has direct load (from storage) and clear inputs.

The 'LS598 comes in a 20-pin package and has all the features of the 'LS597 plus 3-state I/O ports that provide parallel shift register outputs and also has multiplexed serial data inputs.

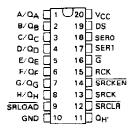
SN54LS597 . . . J OR W PACKAGE SN74LS597 . . . N PACKAGE (TOP VIEW)



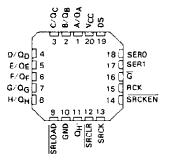
SN54LS597 . . . FK PACKAGE (TOP VIEW)



SN54LS598 . . . J OR W PACKAGE LS598 . . . DW OR N PACKAGE (TOP VIEW)

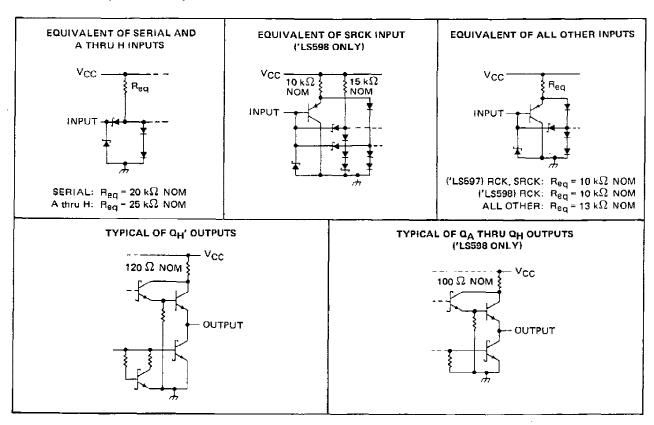


SN54LS598 . . . FK PACKAGE (TOP VIEW)

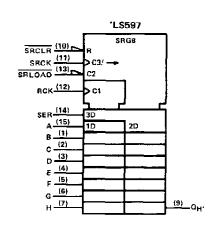


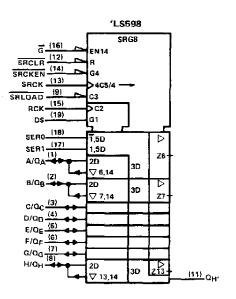
NC - No internal connection

schematics of inputs and outputs



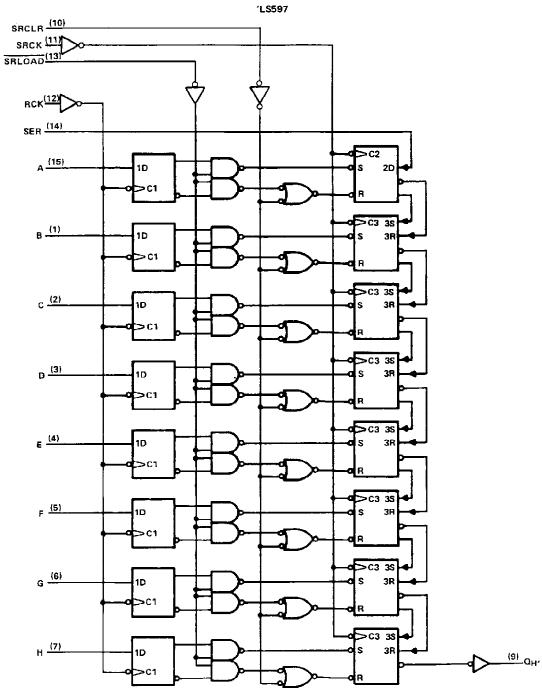
logic symbols †



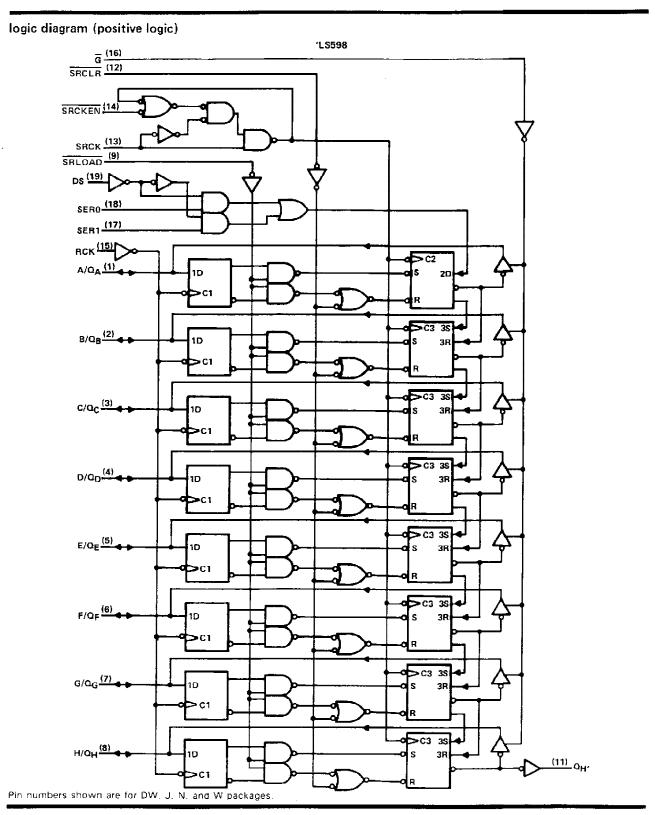


[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.

logic diagram (positive logic)



Pin numbers shown are for DW, J, N, and W packages.



NOTE 1: Voltage values are with respect to the network ground terminal,

recommended operating conditions

				•	,	SN54LS	.*	SN74LS'			UNIT
				1	MIN	NOM	MAX	MIN	NOM	MAX	Civi
Vcc	Supply voltage				4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input v	oltage	je					2			٧
VIL	Low-level input vi	oltage					0.7			0.8	V
	High-level output current		ΩH'		l		- 1			– 1	_ ^
іон			Ω _A thru Ω _H , 'LS598 only				- 1			- 2.6	mA
	Low-level output current		ΩH	QH,			8			16	
IOL			QA thru Q+	, 'L\$598 only	12				24	mA	
fsck	Shift clock freque	псу					20	0		20	MHz
			SRCK	hīgh	15			15			
	Pulse duration		low		35			35			
t _w			RCK SRCLR		20			20			ns
					20			20			
			SRLOAD		40		40				
		Data before F	RCK † ('L\$598 anly) 30 bw before SRCK † ('L\$598 only) 20		20			20			1
	-	DS before SF					30				
		SRCK EN ION			20			20]
t _{su}	Setup time	SRCLR inact	ive before SRCk	C 1	25			25			⊓s
		SRLOAD ina	ctive before SR	CK 1	30			30			
	RCK	RCK † before	SRLOAD † (see Note 2)		40			40			
	SER before SF		ACK t		20			20			
th	Hold time							0			ns
TA	Operating free-air	temperature	emperature				125	0		70	°C

NOTE 2: The RCK 1 before SRLOAD 1 setup time ensures the data saved by RCK 1 will also be loaded into the shift register.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		T		••••t		SN54LS	,	. :	SN74LS	,	UNIT
	PARAMETER	•	EST CONDITIO	NS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	CIVIT
Vik		VCC = MIN,	I _I = - 18 mA				- 1.5			- 1.5	٧
	T	VCC = MIN,	V= 2 V	I _{OH} = - 1 mA	2.4	3.2					
∨он	'LS598 Q	ACC - MAX	VIH - Z V,	10H 5'B IN A				2.4	3.1		V
	α _H ′	VIL-WAX		i _{OH} = - 1 mA	2.4	3.2		2.4	3.2		
	'LS598 Q			I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
Vo∟	C3396 G	V _{CC} = MIN,	$V_{1H} = 2 V$,	IOL = 24 mA					0.35	0.5	v
VOL	ΩH,	V _{IL} ≃ MAX		IOL = 8 mA	0.25 0.4	ļ	0.25	0.4	1		
	ЧН	3		IOL = 16 mA				L	0.35	0.5	
lozh	'L\$598 Q	V _{CC} = MAX, V _O = 2.7 V	V _{IH} = 2 V,	V _{1L} = MAX,			20			20	μA
^l OZL	'LS598 Q	V _{CC} = MAX, V _O = 0.4 V	V _{IH} = 2 V,	VIL = MAX,			- 0.4			- 0.4	mА
	'LS598 Q		V ₁ = 5.5 V V ₁ = 7 V				0.1			0.1	m.A
11	Others	VCC = MAX					0.1	0.1		100	
ЧH	· · · · · · · · · · · · · · · · · · ·	VCC = MAX.	V _I = 2.7 V	•			20			20	μА
	'L\$598 SRCK				Ì		- 0.8			- 0.8	
li L	SER, A Thru H	VCC = MAX,	$V_{CC} = MAX$, $V_1 = 0.4 V$				- 0.4			- 0.4	mA
	Others						- 0.2			- 0.2	
los§	'LS598 Q	Vao≡ MAX	Vo = 0 V		- 30		- 130	- 30		- 130	m.A.
108%	ΩH'	1 100 1100	$V_{CC} = MAX$, $V_O = 0 V$		- 20		– 100	- 20		<u> </u>	
	'LS597 ICCH				<u> </u>	35	53		35	53	
	CCL	V _{CC} = MAX,				35	53		35	53_	mA
Icc	Іссн	All possible inc	outs grounded,			45	68		45	68	
	'LS598 ICCL	All outputs op	en			54	80		54	80	
	I CCZ					56	85		56	85	

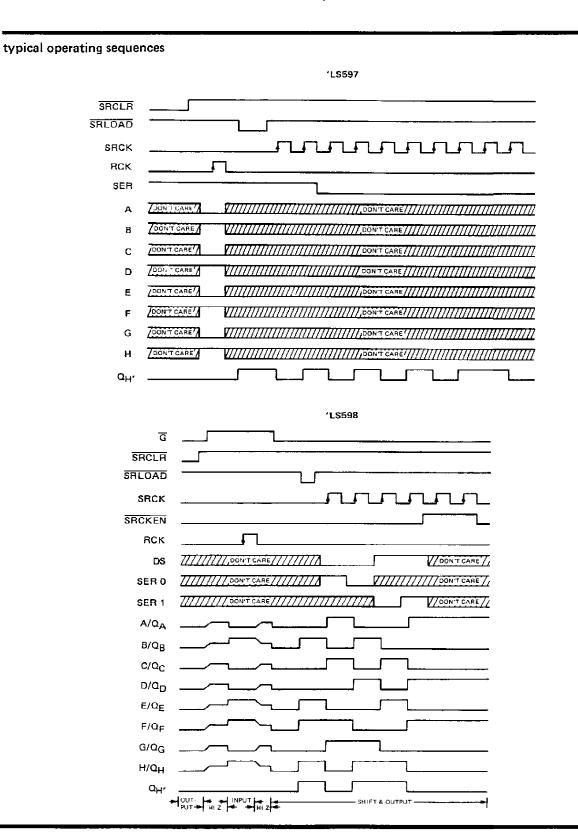
[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $[\]ddagger$ All typical values are at V_{CC} \pm 5 V, T_A \pm 25°C §Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25 \,^{\circ}\text{C}$, (see note 3)

	FROM	то				1 S597	,		'LS598	3	UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST CON	DITIONS	MIN TYP MAX			MiN	TYP	MAX	ONII
fmax	SRCK	a	$R_L = 667 \Omega$,	CL = 45 pF	20	35		20	35		MHz
f _{max}	SRCK	QH'	$R_L = 1 k\Omega$	C _L = 30 pF	20	35					MHz
tPLH	SRCK†	ΩH'				15	23		11	17	ns
tPHL	SPCK1	QH'	D 11.0	0 20 -5		20	30		15	23	กร
†PLH	SRLOAD↓	ΩH,	R _L = 1 kΩ,	C(= 30 pr		38	57		28	42	กร
^T PHL	SRLOAD↓	α _H '				29	44		20	30	ns
t _{PHL}	SRCLR	α _H '				24	36		18	27	ns
^t PLH	RCK1	α _H ′	$R_L = 1 \text{ k}\Omega.$	Ct = 30 pF		41	60		32	48	ns
[†] PHL	RCK1	αH.	SRLOAD = L			32	48		24	36	nş
[†] PLH	SRCKt	a			[12_	18	ns
[†] PHL	SRCK1	α	j						19	28	ПБ
^t PLH	SRLOAD↓	α		C _L = 45 ρF		-			32	48	ns
[†] PHL	SRLOAD↓	α	RL = 667 Ω.						27	40	пѕ
TPHL	SRCLR+	α	_						25	38	ns
[†] PZH	G↓	a							26	31	ns
t PZL	G∔	Q							29	43	ns
t _{PHZ}	Gt	Q	D 667.6	C 55					25	38	ns
tPLZ	Gt	Q	$A_L = 667 \Omega,$	CL = 5 pF					20	30	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





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PACKAGING INFORMATION

C	Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
į	5962-89444012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
	5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
	5962-8944401EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
	5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
	5962-8944401FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
į	5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
į	5962-89756012A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
	5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
	5962-8975601SA	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI
	SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
	SN54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
	SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
	SN54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
	SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS597D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS597DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
;	SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS597DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
	SN74LS597N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
	SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
	SN74LS597NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
;	SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
;	SN74LS597NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
S	N74LS597NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LS597NSRG4	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SI	N74LS597NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
	SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

PACKAGE OPTION ADDENDUM

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Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS598N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS598NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS597W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS598W	OBSOLETE			20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS597NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

I	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	SN74LS597NSR	SO	NS	16	2000	346.0	346.0	33.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

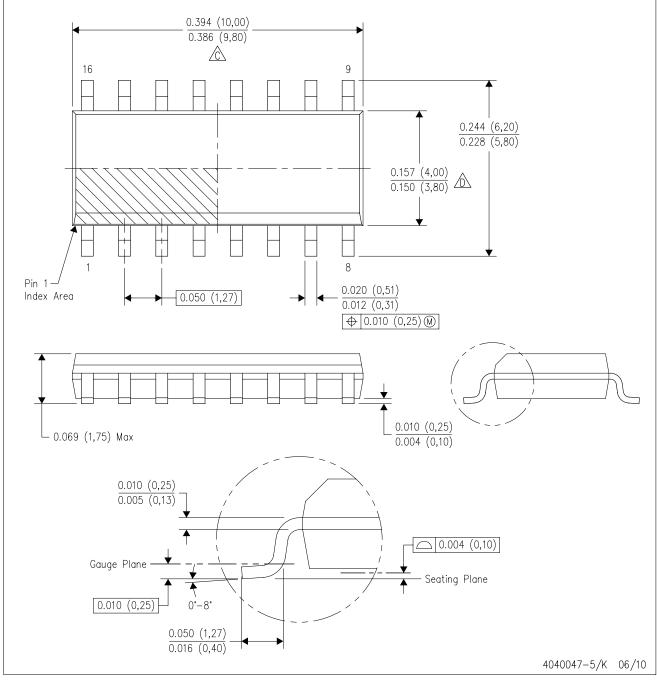


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDS0-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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